



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**PATENT**

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Application No.: 09/464,322  
Filing Date: December 15, 1999  
Applicant: Heung-Kyu KWON et al.  
Group Art Unit: 2815  
Examiner: Chris C. CHU  
Title: SEMICONDUCTOR CHIP PACKAGE AND METHOD OF  
FABRICATING THE SAME  
Attorney Docket: 25611-000085/US

Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314  
**Mail Stop AF Amendment**

September 14, 2006

**AMENDMENT AFTER FINAL REJECTION UNDER 35 CF.R. § 1.116**

Sir:

In response to the Office Action mailed June 21, 2006, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Specification begin on page 2 of this Amendment.

Amendments to the Claims begin on page 3 of this Amendment.

Remarks begin on page 7 of this Amendment.

	Claims remaining after Amendment		Highest number previously paid for		Present extra
Total	18	-	20	=	0
Independent	3	-	3	=	0